## APPLICATION DATA SHEET PROCUPOTO 12 APR 2006

Inventor

**MAEKAWA** 

438-0039

Iwata, Shizuoka

3-12-3, Toushin-cyo,

c/o Semiconductor Energy Laboratory Co., Ltd.

Iwata-shi, Shizuoka-ken

JP

JP

JP

Shinji

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AD	olicai	nt In	form	ation:
	<i></i>			

Inventor 1:

**Applicant Authority Type:** 

Citizenship:

Given Name:

Family Name:

City of Residence:

Country of Residence:

Address-1 of Mailing Address:

Address-2 of Mailing Address:

City of Mailing Address:

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address:

Phone:

E-mail:

Fax:

Inventor 2:

**Applicant Authority Type:** 

Citizenship:

Given Name:

Family Name:

City of Residence:

Country of Residence:

Address-1 of Mailing Address:

Address-2 of Mailing Address:

City of Mailing Address:

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address:

Phone:

E-mail:

Fax:

JP

Inventor

Shunpei

YAMAZAKI

398, Hase,

243-0036

Setagaya, Tokyo

Atsugi-shi, Kanagawa-ken

JP

JP

4/6/2006

Inventor 3:				
Applicant Authority Type:	Inventor			
Citizenship:	JP			
Given Name:	Yuko			
Family Name:	TACHIMURA			
City of Residence:	Atsugi, Kanagawa			
Country of Residence:	JP			
Address-1 of Mailing Address:	c/o Semiconductor Energy Laboratory Co., Ltd.			
Address-2 of Mailing Address:	398, Hase,			
City of Mailing Address:	Atsugi-shi, Kanagawa-ken			
State of Mailing Address:				
Postal Code of Mailing Address:	43-0036			
Country of Mailing Address:	JP			
Phone:				
Fax:				
E-mail:				
Inventor 4:				
Applicant Authority Type:	Inventor			
Citizenship:	JP			
Given Name:	Koji			
Family Name:	MURANAKA			
City of Residence:	Kumamoto, Kumamoto			
Country of Residence:	JP			
Address-1 of Mailing Address:	4-33, Idenakama,			
Address-2 of Mailing Address:				
City of Mailing Address:	Kumamoto-shi, Kumamoto-ken			
State of Mailing Address:				
Postal Code of Mailing Address:	862-0963			
Country of Mailing Address:	JP			
Phone:				
Fax:				
E-mail:				
Correspondence Information:				

22204

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**Customer Number:** 

Application Information:

Title of Invention:

METHOD FOR FORMING WIRING, METHOD FOR

MANUFACTURING THIN FILM TRANSISTOR OR AND

DROPLET DISCHARGING METHOD

Application Type:

regular, utility

Attorney Docket Number: 740756-2947

**Botanic Information:** 

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Domestic Priority Information:

This is a National Stage of JP application number PCT/JP2004/016181, filed 2004-10-25, now pending.

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Doc.No:2003-368038; Country - JP; Date: 2003-10-28 us-priority-claimed

Assignee Information:

Assignee 1:

Organization Name:

Semiconductor Energy Laboratory Co., Ltd.

Address-1 of Mailing Address:

398, Hase,

Address-2 of Mailing Address:

City of Mailing Address:

Atsugi-shi, Kanagawa-ken

State of Mailing Address:

Postal Code of Mailing Address: 243-0036

Country of Mailing Address:

JΡ

Phone:

Fax:

E-mail: